

Please add the following new claims.

30. (New) The method of claim 24 wherein the metal layer comprises copper.
31. (New) The method of claim 24 wherein the bumps in the plurality of bumps are disposed in an array.
32. (New) The method of claim 24 wherein the bumps in the plurality of bumps are arranged around a die attach region.
33. (New) The method of claim 24 wherein a dielectric layer is on the metal layer.
34. (New) The method of claim 24 wherein the metal layer includes one or more sublayers of material on a base metal.
35. (New) The method of claim 24 wherein the metal layer is discontinuous and includes a plurality of etched conductive lines that lead to the plurality of bumps.
36. (New) The method of claim 24 wherein each bump has a conical angle of about 40 degrees or more.
37. (New) The method of claim 24 wherein the plurality of bumps are formed simultaneously in the metal layer.

REMARKS

This Amendment is responsive to the Office Action mailed on October 22, 2002.

Election

In the Office Action, the Examiner restricts the claims into two Groups, Group I (claims 1-3, 5-10 and 12-23) and Group II (claims 24 and 26-29). In response to the Office Action, Applicant elects Group II, claims 24 and 26-29, with traverse.

Applicant submits that the search and examination of the Group I and II claims would not be burdensome. Both Groups I and II have already been searched and examined (see the Office Action mailed March 18, 2002). Thus, withdrawal of the restriction is requested. However, to expedite the prosecution, the claims of Group I are canceled.

Status of Claims

In this Amendment, claims 1-3, 5-10, 12-23, and 28 are canceled, claims 24, 26, 29 are unamended, claim 27 is amended, and new dependent claims 30-37 are added. New dependent claims 30-37 are method claims within the Group of claims elected for examination. Claims 24, 26, 27, and 29-37 are subject to examination.

As Applicant has now elected a Group of claims for examination, the Examiner is requested to consider the pending claims and the arguments made in the Amendment filed on July 18, 2002 (via certificate of mailing). Applicant believes that all claims are in condition for allowance for the reasons provided in the July 18, 2002 Amendment. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 415-273-7529.

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

Claims 1-23 and 25 are canceled.

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24. (Unamended) A method for forming a carrier for a semiconductor die package, the method comprising:

- (a) providing a metal layer; and
- (b) forming a plurality of bumps in the metal layer, wherein the formed bumps are capable of being electrically coupled to conductive regions of a circuit substrate, and wherein forming the plurality of bumps comprises stamping.

26. (Unamended) A method for forming a semiconductor die package, the method comprising:

- (a) forming a carrier according to the method of claim 24; and
- (b) attaching a semiconductor die to the metal layer after forming the plurality of bumps.

27. (Amended) The method of claim 26 wherein [(c)] attaching comprises: attaching the semiconductor die to a die attach region of the carrier, and wherein the plurality of bumps is disposed around the semiconductor die.

29. (Unamended) The method of claim 24 wherein the bumps each have a conical shape.

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30. (New) The method of claim 24 wherein the metal layer comprises copper.

31. (New) The method of claim 24 wherein the bumps in the plurality of bumps are disposed in an array.

sub c1 → 32. (New) The method of claim 24 wherein the bumps in the plurality of bumps are arranged around a die attach region.

33. (New) The method of claim 24 wherein a dielectric layer is on the metal layer.

34. (New) The method of claim 24 wherein the metal layer includes one or more sublayers of material on a base metal.

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35. (New) The method of claim 24 wherein the metal layer is discontinuous and includes a plurality of etched conductive lines that lead to the plurality of bumps.

sub c1 → 36. (New) The method of claim 24 wherein each bump has a conical angle of about 40 degrees or more.

37. (New) The method of claim 24 wherein the plurality of bumps are formed simultaneously in the metal layer.